

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-6. (canceled).

7. (new): A semiconductor wafer processing method, comprising adhering a removable pressure-sensitive adhesive sheet which comprises a pressure-sensitive adhesive layer which is made of at least a pressure-sensitive adhesive comprising a polymer in which the content of low-molecular components having a molecular weight of 10^5 or lower is 10% by weight or lower, and the polymer has a weight average molecular weight of 930,000 to 2,100,000, to a front or back surface of the wafer, and processing the wafer.